

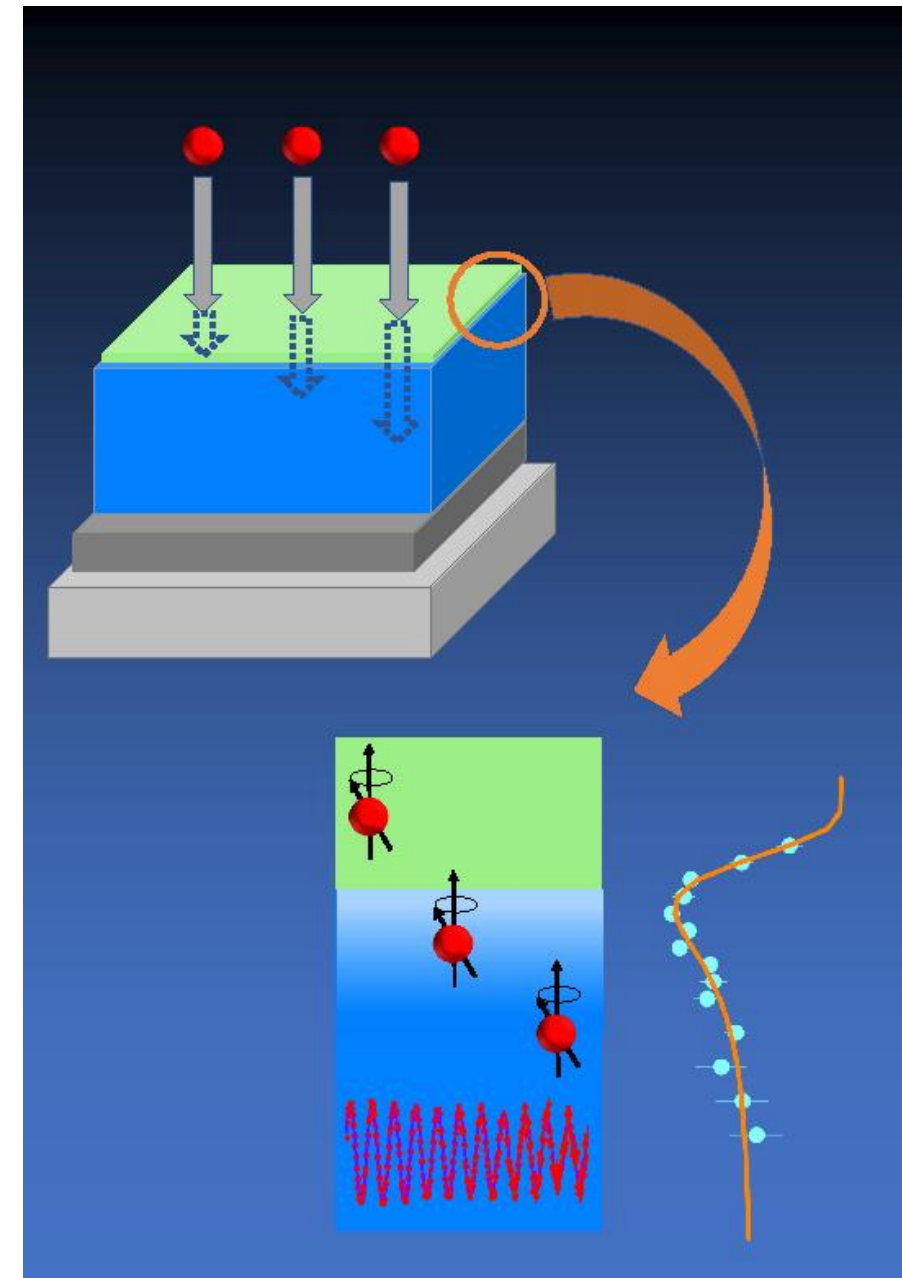
# Low energy muon study of the p-n interface in chalcopyrite solar cells

Coimbra group: Helena V. Alberto, R. Vilão, E. Ribeiro, J. M Gil, A. Weidinger

INL group: Pedro Salomé, Marco Curado, Jennifer Teixeira, José Cunha

Uppsala: Marika Edoff

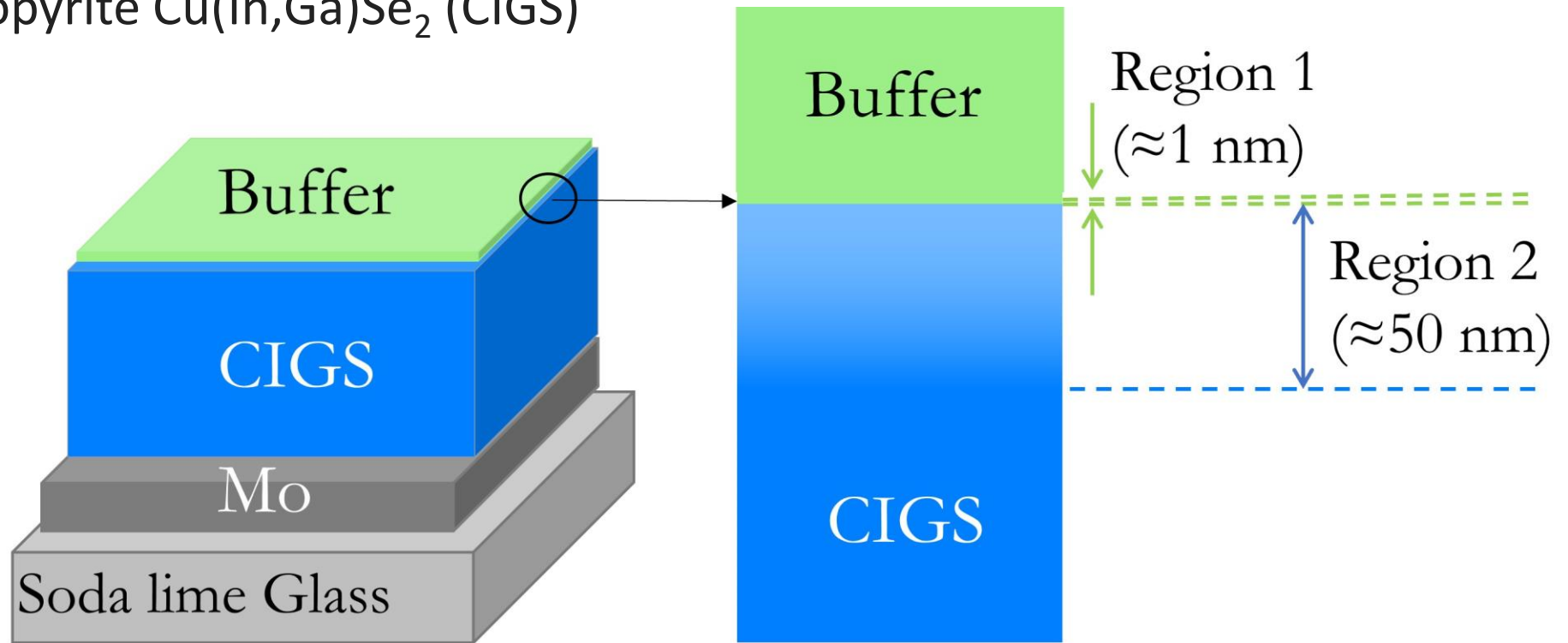
LEM team: Maria Martins, Thomas Prokscha, Zaher Salman



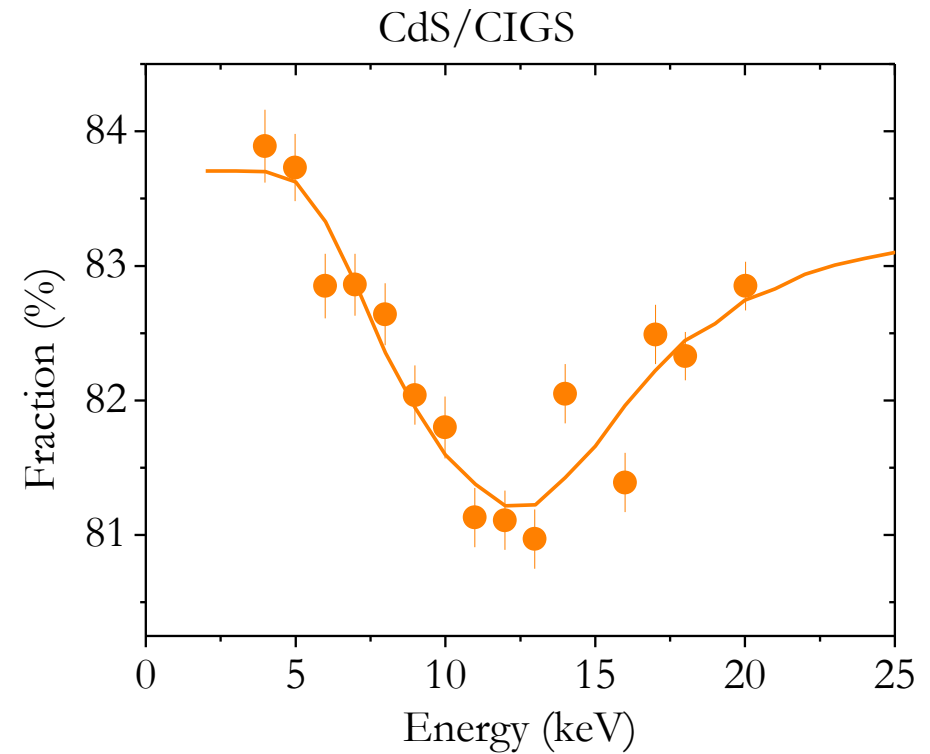
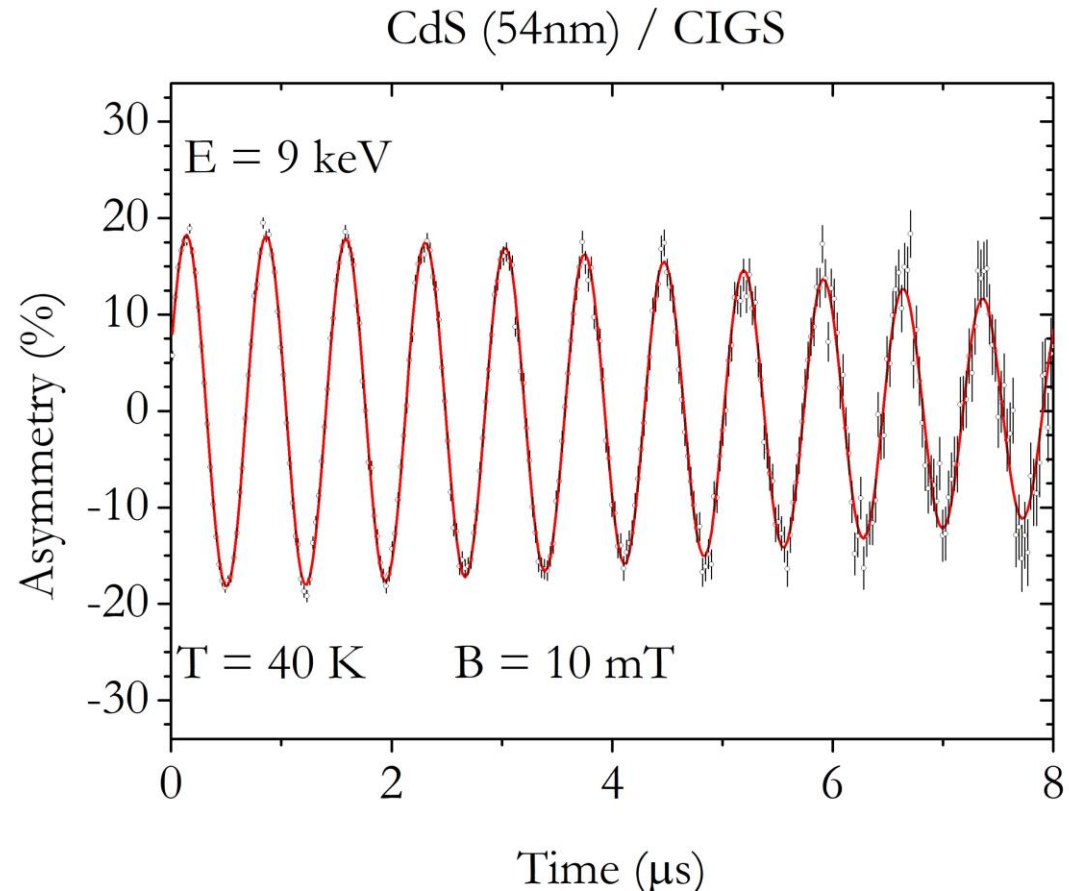
# Samples

cover layer: CdS, ZnSnO, Al<sub>2</sub>O<sub>3</sub> and SiO<sub>2</sub>

Absorber: chalcopyrite Cu(In,Ga)Se<sub>2</sub> (CIGS)



# LEM measurements

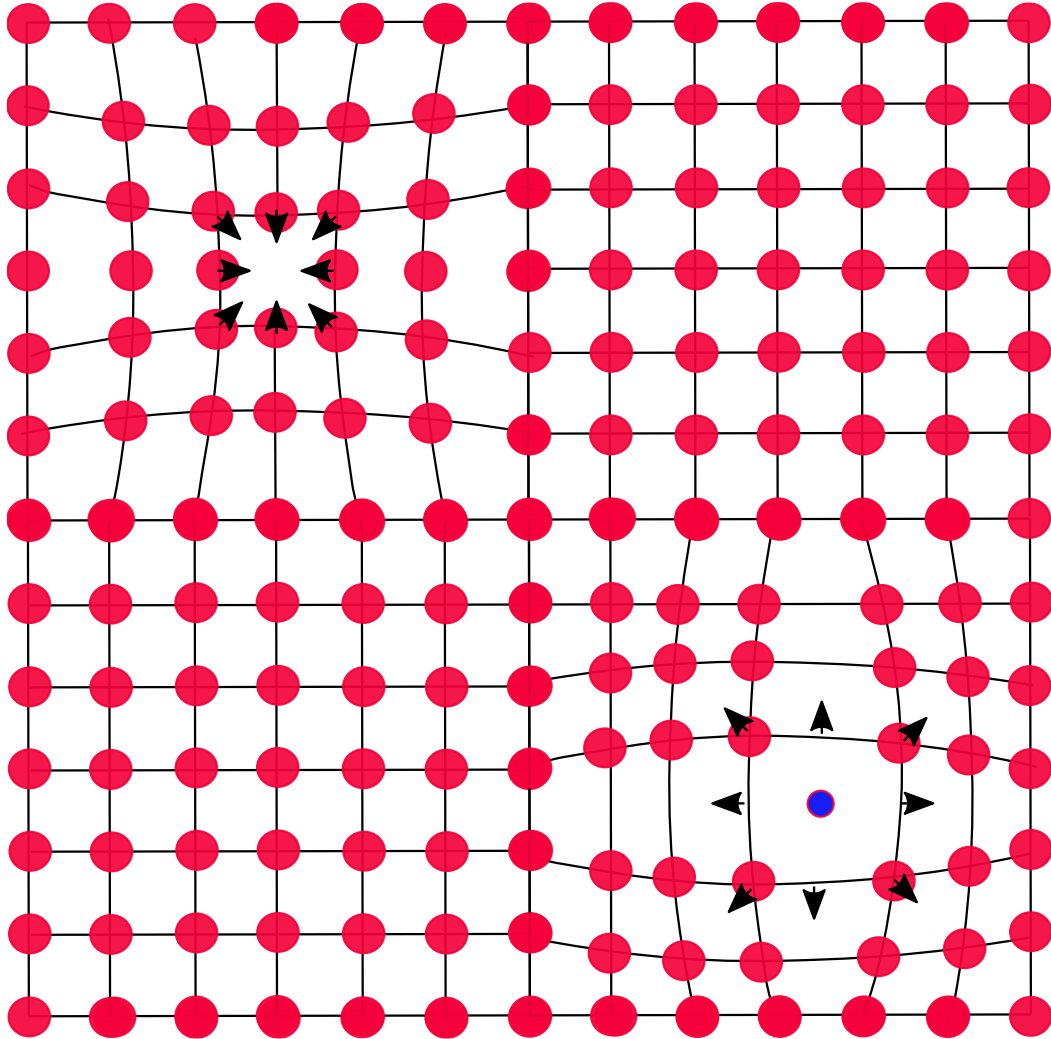


change of diamagnetic fraction with implantation energy

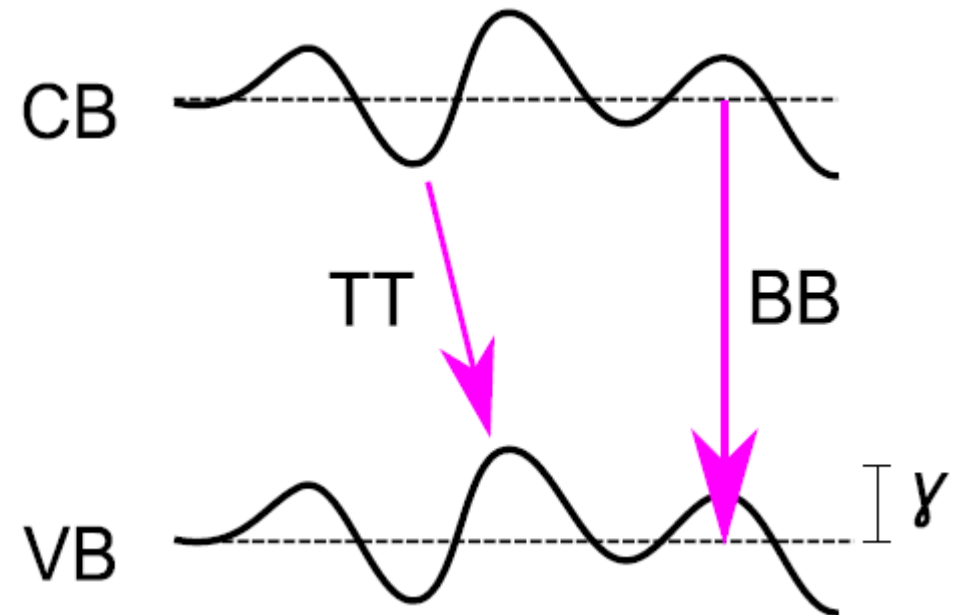


1. What causes the dip?
2. Where is the dip situated (in CIGS? in the cover layer? in both?) ?

# Defect-induced strain fields

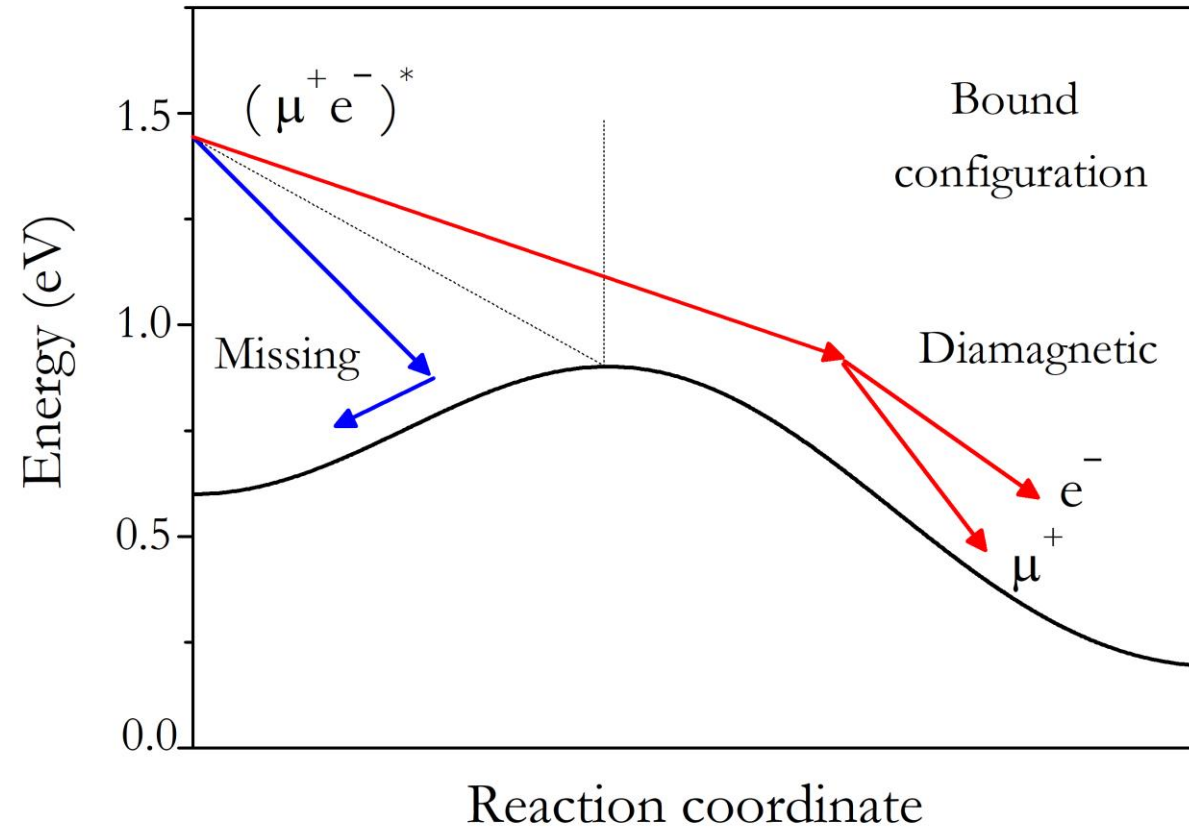


# Electron Potential Fluctuations (tail states)



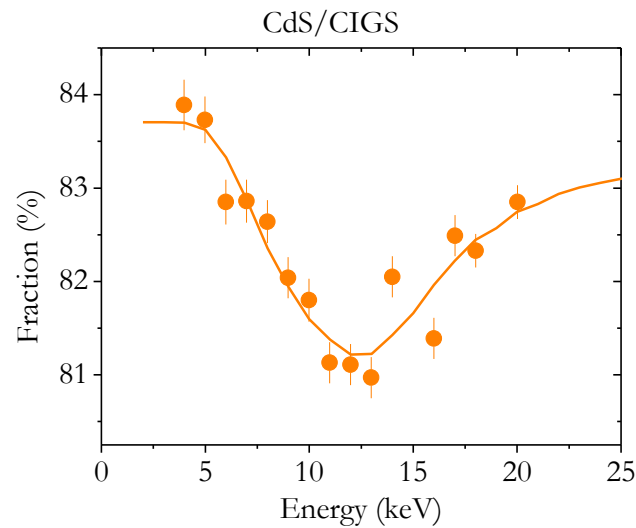
# The model

- The formation of the diamagnetic bound state requires lattice rearrangement, which can be described as a potential barrier.
- Lattice strain induced by defects increases the barrier height and reduces the formation probability of the bound diamagnetic state.
- That is the origin of the dip in the diamagnetic signal: the muon probe is sensing a defect region.



# Where is the dip situated?

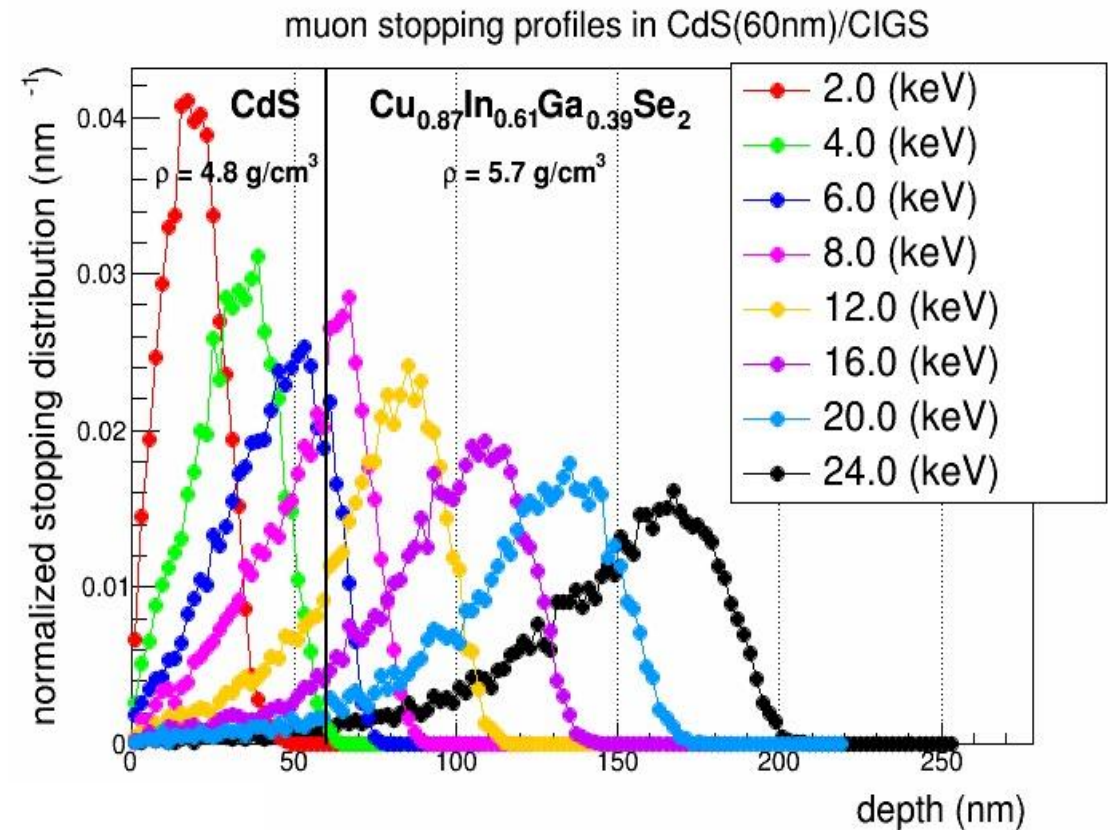
## Using resolution information from TRIM.SP



$$f_{\text{dia}}^{\text{exp.}}(E) = \int_0^{\infty} P(x, E) f_{\text{dia}}(x) dx$$

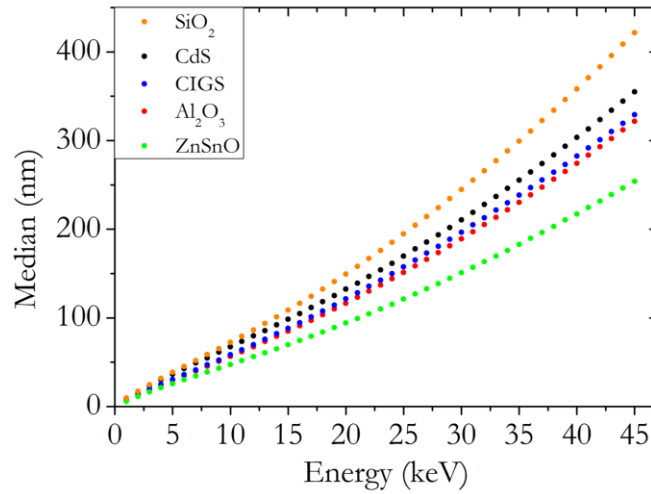
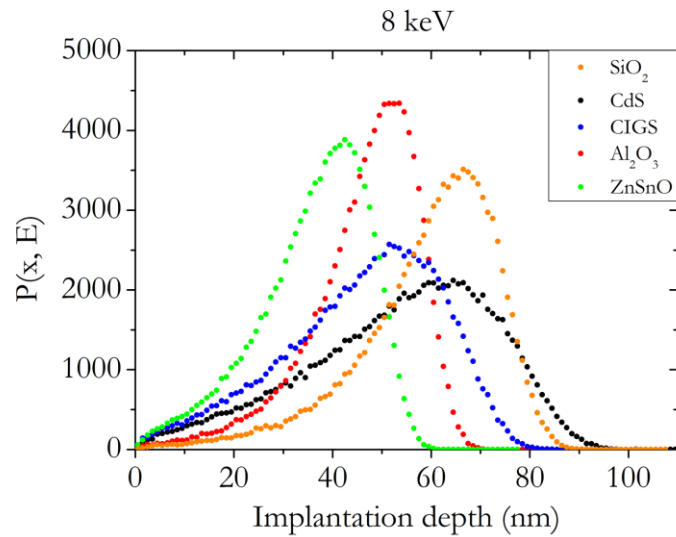
- The experimental  $f_{\text{dia}}(E)$  is the result from a convolution of the real  $f_{\text{dia}}(x)$  with the normalized stopping distribution  $P(x, E)$ , obtained by Monte Carlo simulations (TRIM.SP).

The real profile  $f_{\text{dia}}(x)$  is washed out because not all muons stop at the same depth.



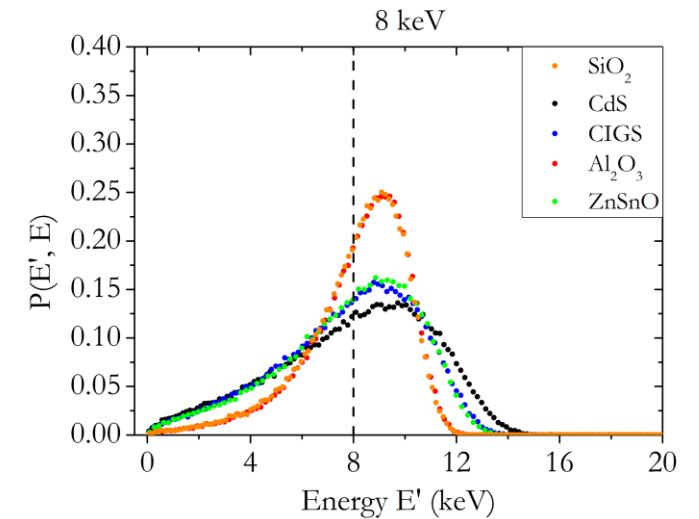
# Unfolding the depth profile

poster session I : #145 Ribeiro et al. "Unfolding of the depth profiles with universal-range distribution functions"



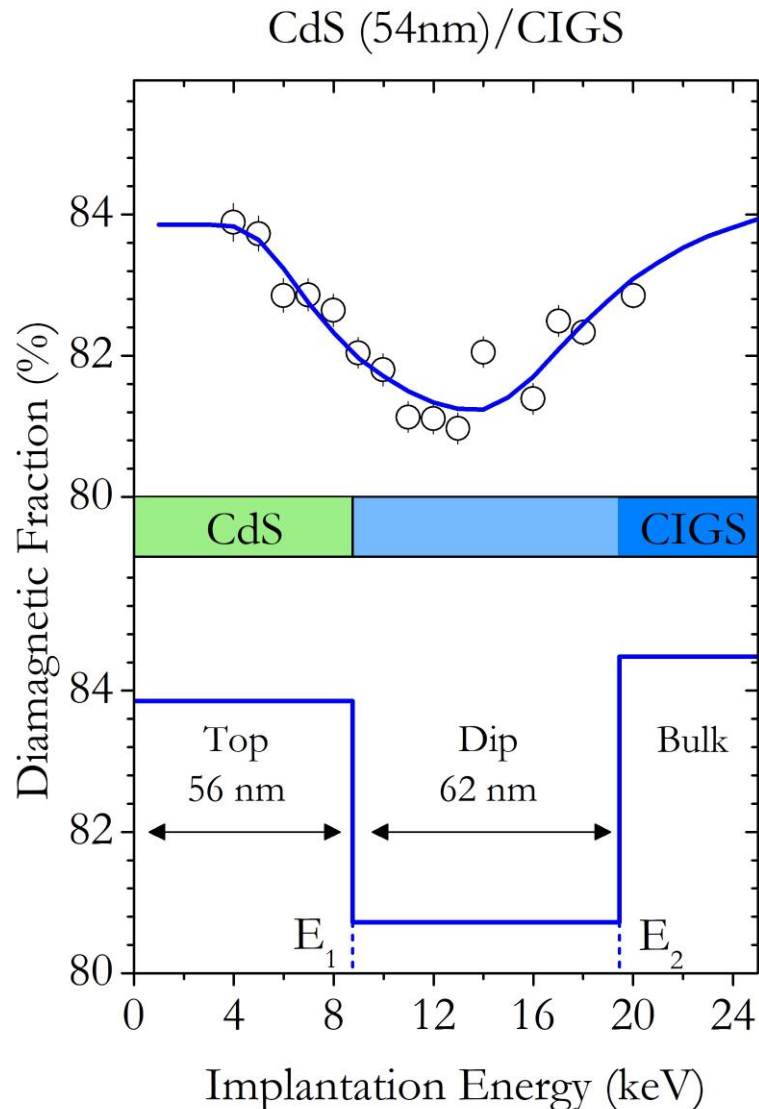
$$x = f(E')$$

$$P(E', E)dE' = P(x, E)dx = P(x, E) \frac{dx}{dE'} dE'$$



$$f_{\text{dia}}^{\text{exp.}}(E) = \int_0^{\infty} P(E', E) f_{\text{dia}}(E') dE'$$

# results



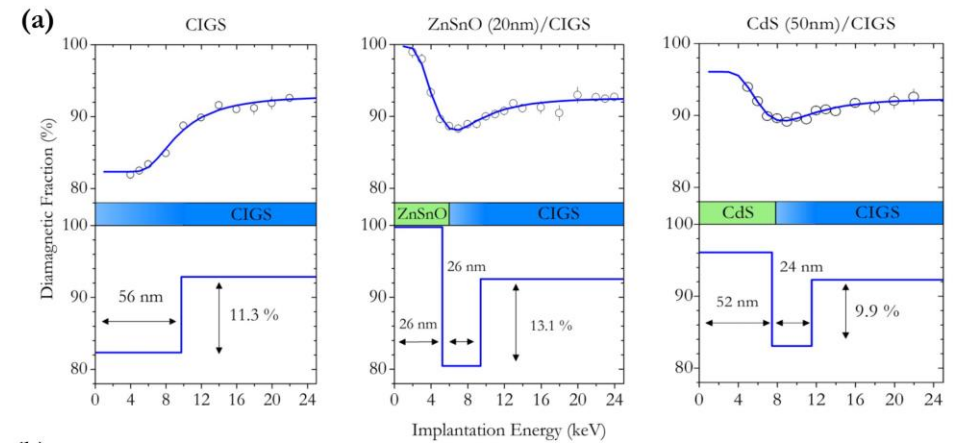
$$f_{\text{dia}}^{\text{exp.}}(E) = \int_0^{\infty} P(E', E) f_{\text{dia}}(E') dE'$$

- the trial function for  $f_{\text{dia}}(E')$  is a simple three step function with 5 adjustable parameters. A fit is performed to obtain the parameters that lead to the best description of the experimental data  $f_{\text{dia}}^{\text{exp.}}(E)$
- the relation  $x = f(E')$  is used to convert  $E_1$  and  $E_2 - E_1$  in widths measured in nm.
- The best fit to the trial function shows that the lattice is more perturbed **in the near-interface region, on the side of the absorber**, than further inward in the sample.

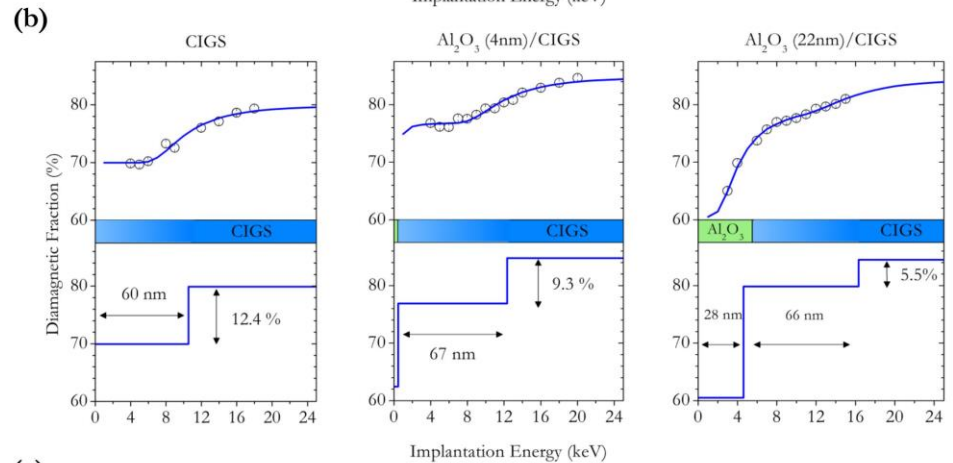


# Changing cover layers

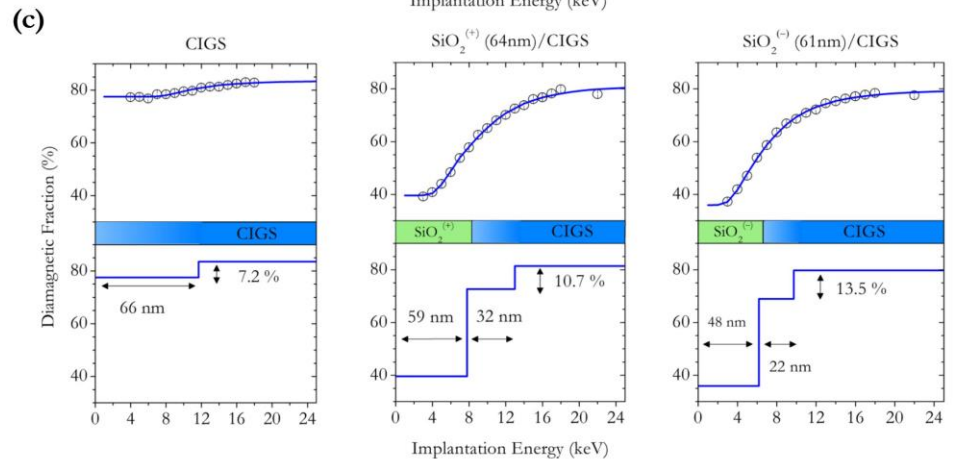
(a) : uncovered CIGS and the effect of ZnSnO and CdS covers



(b) : effect of Al<sub>2</sub>O<sub>3</sub> with different widths on the same uncovered CIGS

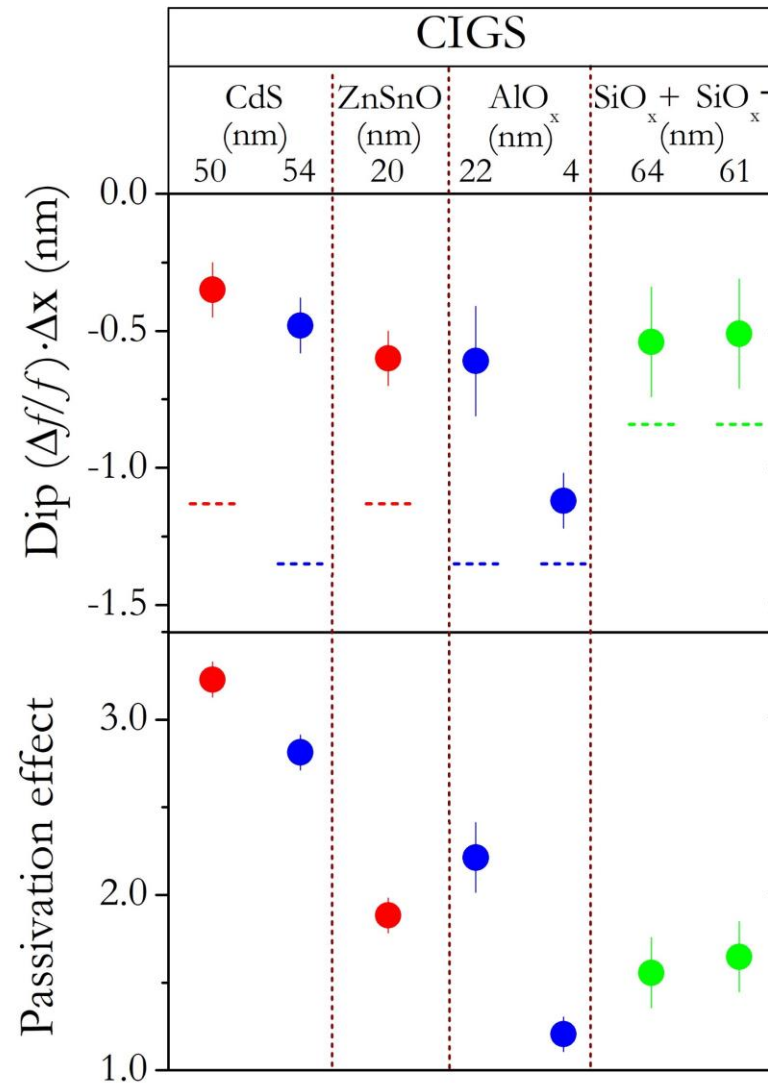


(c) : effect of SiO<sub>2</sub> with different surface charges on the same uncovered CIGS



# Measuring passivation of bulk defects near the p-n junction

- the passivation effect near the p-n region is quantified : it is defined as the dip size of the uncovered film divided by the dip size of the covered film.
- CdS provides the best defect passivation.
- Oxide materials are less effective.



# Conclusions

- Slow muons are sensitive only to a region near the p-n interface (region 2), which is more disturbed than the inner part of CIGS.
- A disturbed interface region is associated with interface recombination losses, affecting the device efficiency. It is important to distinguish contributions from regions 1 and 2.
- Slow muons allows us to separate contributions from region 1 and 2, not possible with other techniques.
- Using slow muons, it is possible to make a quantitative characterization of the effect of various buffer/cover layers on the passivation of bulk defects in this region.

